Negative Voltage SPDT Switch

The NLHV3157N is an advanced CMOS analog switch fabricated with silicon gate CMOS technology. The device passes analog and digital negative voltages that may vary across the full power–supply range (from V_{EE} to GND).

Features

- Operating Voltage Range: $V_{EE} = -12 \text{ V to } -4 \text{ V}$
- Switch Signal Voltage Range: $V_{IS} = V_{EE}$ to GND
- Positive Control Signal Voltage: $V_{IN} = 0$ to 3.3 V
- Low ON Resistance: $R_{ON} \le 5 \Omega$ @ $V_{EE} = -10 V$
- Latch-up Performance Exceeds 200 mA
- Available in: SC88 6-Pin Package
- These Devices are Pb–Free, Halogen–Free/BFR-Free and are RoHS–Compliant

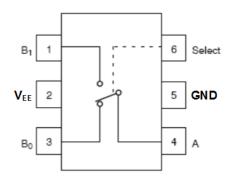


Figure 1. Pin Assignment and logic Diagram





MARKING

DIAGRAM

N7 = Device Code M = Date Code* = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

FUNCTION TABLE

Select Input	Function	
L	B0 Connected to A	
н	H B1 Connected to A	

ORDERING INFORMATION

Device	Package	Shipping [†]
NLHV3157NDFT2G	SC88 (Pb–Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Symbol	Rating	g	Value	Unit
V_{EE}	DC Supply Voltage		-13 to +0.5	V
V _{IS}	Analog Input Voltage (Note 1)		V _{EE} -0.5 to +0.5	V
V _{IN}	Digital Select Input Voltage (Note 1)		-0.5 to +3.6	V
I _{IOK}	Switch Input/Output diode current		±50	mA
Ι _{ΙΚ}	Select input diode current		-50	mA
PD	Power Dissipation in Still Air		60	mW
ΤL	Lead Temperature, 1 mm from Case for 1	0 seconds	260	°C
TJ	Junction Bias Under Bias		150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 30% – 35%	UL94–V0 (0.125 in)	°C
١L	Latch-up Current (Note1)	Below GND and above V _{EE} at 125°C	±200	mA
		Below GND and above V_{EE} at 25°C	±300	
Ts	Storage Temperature		-65 to +150	°C
θ_{JA}	Thermal Resistance		400	°C/W
ESD	ESD Protection	Human Body Model	3000	V
		Machine Model	150	1

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. The input and output voltage ratings may be exceeded if the input and output diode current ratings are observed.

RECOMMENDED OPERATING CONDITIONS (Note 2)

Symbol	Parameter		Max	Unit
V _{EE}	DC Supply Voltage	-12	-4	V
VS	Switch Input / Output Voltage (B0, B1, A)	V _{EE}	GND	V
V _{IN}	Digital Select Input Voltage	GND	3.3	V
T _A	Operating Temperature Range	-55	+125	°C
t _r , t _f	Input Transition Rise or Fall Time (Select Input)	0	100	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.Select input must be held HIGH or LOW, it must not float.

DC ELECTRICAL CHARACTERISTICS (Voltages referenced to GND; Typical characteristics are T_A at 25°C.)

				-	-55° to 125°		
Symbol	Parameter	Condition	V _{EE} , V	Min	Тур	Max	Unit
SELECT IN	PUT					1	
VIH	Minimum High–Level		< -10	2.0		3.3	V
	Input Voltage		−10 to < −8	1.8		3.3	+
			-8 to < -6	1.7		3.3	1
			≥ -6	1.4		3.3	1
V _{IL}	Maximum Low-Level		< -10	0		0.7	V
	Input Voltage		-10 to -6	0		0.7	-
			−8 to < −6	0		0.7	1
			≥ -6	0		0.5	
I _{IN}	Maximum Input Leakage Current	$V_{IN} = 3.3 \text{ V or GND}$	-10		±0.2	±20	μA
POWER SL	JPPLY						
I _{CC}	Maximum Quiescent Supply Current	Select = 3.3 V or GND , V _{IS} = V _{EE} or GND	-10 to -4		25	50	μA
ANALOG S	WITCH						
R _{ON}	Maximum ON Resistance (Note 3)		-12		2.6	4.5	Ω
Resistanc			-10		3.0	5	
			-8		3.5	5.8	
			-6		4.5	7.5	1
		$V_{IN} = V_{IL} \text{ or } V_{IH}$ $V_{IS} = V_{EE} \text{ to GND}$ $I_O \le 5 \text{ mA}$	-4		9	15	
R _{FLAT}	ON Resistance	$V_{IN} = V_{IL} \text{ or } V_{IH}$ $V_{IS} = V_{EE} \text{ to GND}$ $I_O \le 10 \text{ mA}$	-12		0.4		Ω
	Flatness (Notes 3, 4, 6)		-10		1.2		
			-8		1.7		
			-6		2.5		1
		$V_{IN} = V_{IL} \text{ or } V_{IH}$ $V_{IS} = V_{EE} \text{ to GND}$ $I_O \le 5 \text{ mA}$	-4		6		
ΔR_{ON}	R _{ON} Mismatch	I _A = –10 mA, V _{Bn} = –8.4 V	-12		0.2		Ω
	Between (Notes 3, 4, 5)	I _A = -10 mA, V _{Bn} = -7 V	-10		0.2		
		I _A = –10 mA, V _{Bn} = –5.6 V	-8		0.25		
		I _A = -10 mA, V _{Bn} = -4.2 V	-6		0.25		-
		I _A = -5 mA, V _{Bn} = -2.8 V	-4		0.3		1
I _{NC(OFF)} , I _{NO(OFF)}	NC or NO OFF Leakage Current (Figure 9)	$V_{IN} = V_{IL} \text{ or } V_{IH}, V_{Bn} = GND, V_A = V_{EE} \text{ to } GND$	-10		±1.0	±20	μΑ
ICOM(ON)	COM ON Leakage Current (Figure 9)	$ \begin{array}{l} V_{IN} = V_{IL} \mbox{ or } V_{IH}; \\ V_A = GND \mbox{ V or } V_{EE}; \\ V_{B1} = GND \mbox{ or } V_{EE} \mbox{ with } V_{B0} \\ \mbox{ floating, or } \\ V_{B0} = GND \mbox{ or } V_{EE} \mbox{ with } V_{B1} \\ \mbox{ floating} \end{array} $	-10		±2.0	±20	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Measured by the voltage drop between A and B pins at the indicated current through the switch. On Resistance is determined by the lower

of the voltages on the two (A or B Ports).

4. Parameter is characterized but not tested in production.

5. ΔR_{ON} = R_{ON}max - R_{ON}min measured at identical V_{EE}, temperature and voltage levels.
6. Flatness is defined as the difference between the maximum and minimum value of ON Resistance over the specified range of conditions.

				–55° to 125°C			
Symbol	Parameter	Condition	V _{EE} , V	Min	Тур	Max	Unit
t _{PHL} , t _{PLH}	Propagation Delay, Bus to Bus (Note 8) (A to B _n)	C _L = 100 pF (Figures 2, 3)	-12 to -4			2	ns
t _{PZL} , t _{PZH}	Switch Enable Time	C _L = 100 pF (Figures 2, 3)	-12			220	ns
	Turn–On Time (A to B _n)		-10			175	
	(A 10 B _n)		-8			165	
			-6			165	
			-4			200	
t _{PLZ} , t _{PHZ}	Switch Disable Time	C _L = 100 pF (Figures 2, 3)	-12			225	ns
	Turn-Off Time		-10			155	
	(A to B _n)		-8			150	
			-6			120	1
		-4			145		
t _B	Switch Break Time	$R_{L} = 50 \Omega, C_{L} = 100 \text{ pF},$	-12	10		50	ns
		$V_{IS} = -2.5 V (Figure 4)$	-10	10		60	
			-8	20		75	
			-6	20		90	
			-4	50		135	
t _{POR}	Power ON Reset Time	Measured from $V_{EE} = -4 V$	-12 to -4			20	μs
Q	Charge Injection $C_L = 1 \text{ nF}, V_{GEN} = 0 \text{ V},$	-12		170		рС	
	(Note 7)	$R_{GEN} = 0 \Omega$ (Figure 5)	-10		120		
			-8		95		
			-6		55		
			-4		40		
OIRR	Off–Isolation (Note 9)	$R_L = 50 \Omega$, f = 10 MHz (Figure 6)	-12 to -4		-33		dB
Xtalk	Crosstalk	$R_L = 50 \Omega$, f = 10 MHz (Figure 7)	-12 to -4		-42		dB
BW	–3 dB Bandwidth	$R_L = 50 \Omega$ (Figure 10)	-12 to -4		200		MHz

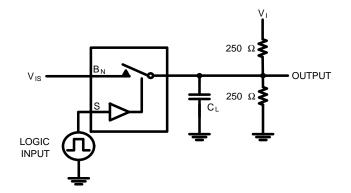
AC ELECTRICAL CHARACTERISTICS (Voltages referenced to GND; Typical characteristics are T_A at 25°C.)

Guaranteed by Design.
 This parameter is guaranteed by design but not tested. The bus switch contributes no propagation delay other than the RC delay of the ON Resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).
 Off Isolation = 20 log10 [VA/VBn].

CAPACITANCES (Note 10)

Symbol	Parameter	Test Conditions	Typical @ 25°C	Unit
C _{IN}	Input Capacitance, Select Inputs	V _{EE} = -12 V	6	pF
C _{IOB}	B–Port OFF Capacitance	V _{EE} = -10 V	45	pF
C _{IOA_ON}	A Port Capacitance when Switch is Enabled	V _{EE} = -10 V	100	pF

 $10. T_A = +25^{\circ}C$, f = 1 MHz, Capacitance is characterized but not tested in production.



Note: Input V_{IS} driven by 50 Ω source terminated by 50 Ω . Note: C_L includes load and stray capacitance. Input PRR = 100 kHz, t_W = 5 μ s.

Parameter	VI	V _{IS}
t _{PLH} / t _{PHL}	Open	Source
t _{PZL} / t _{PLZ}	GND	V _{EE}
t _{PZH} / t _{PHZ}	2 x V _{EE}	GND

Figure 2. AC Test Circuit

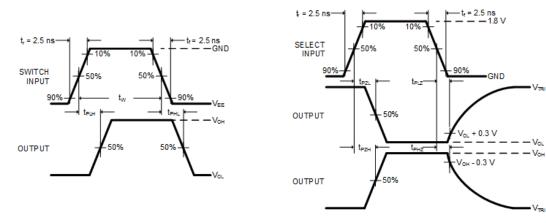


Figure 3. AC Test Waveforms

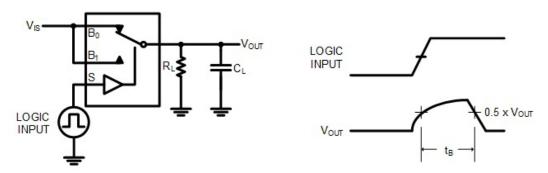
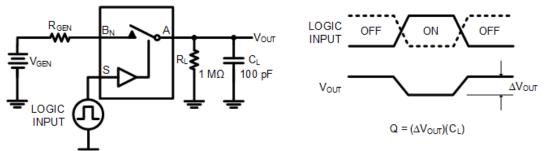
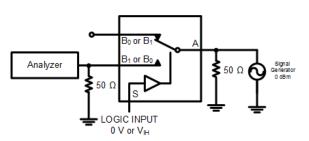


Figure 4. Switch Break Interval Timing









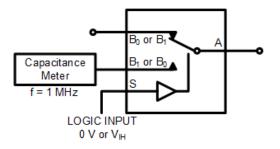


Figure 8. Channel Off Capacitance

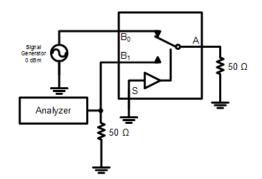


Figure 7. Crosstalk

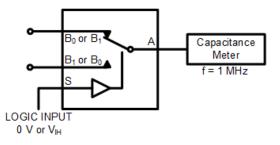


Figure 9. Channel On Capacitance

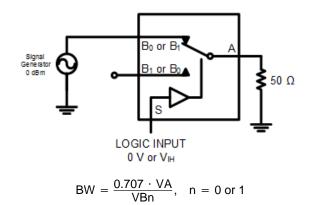
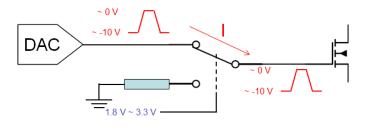


Figure 10. Bandwidth



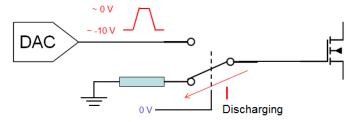
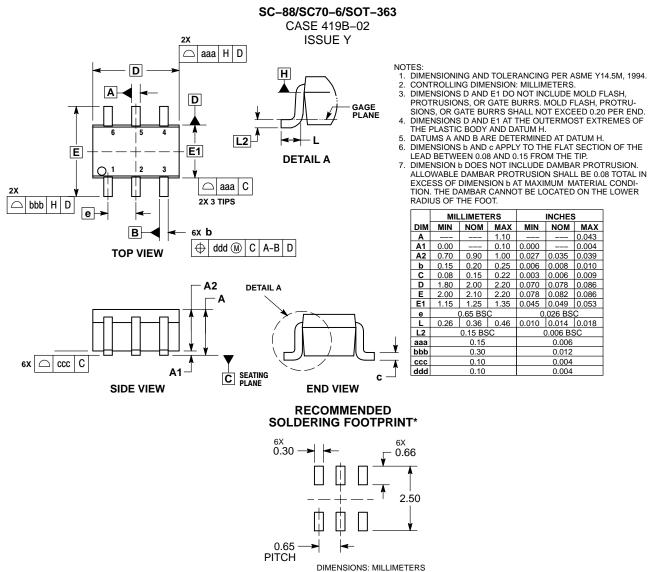


Figure 11. Typical Application

PACKAGE DIMENSIONS



INCHES

MIN NOM MAX

0.027 0.035 0.039

0.026 BSC

0.010 0.014 0.018

0.006 BSC

0.006

0.012

0.004

0.004

2.200.0700.0780.0862.200.0780.0820.086

1.10

1.00

0.10 0.000

0.043

0.004

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.